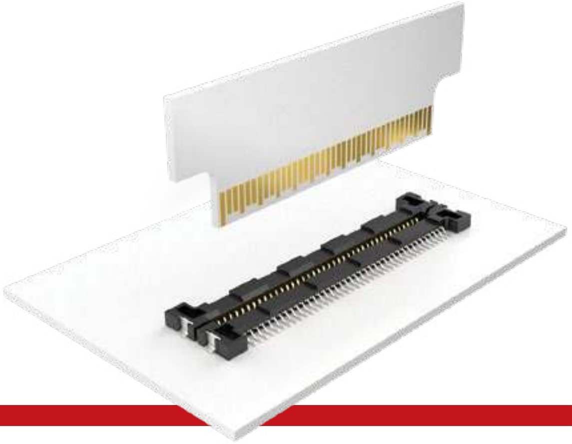
HIGH-SPEED THROUGH BOARD SOCKET

14 Gbps

(1.00 mm) .0394" PITCH • SAL1 SERIES



SAL1

Card Mates:
(1.60 mm) .062" or
(2.36 mm) .093" card

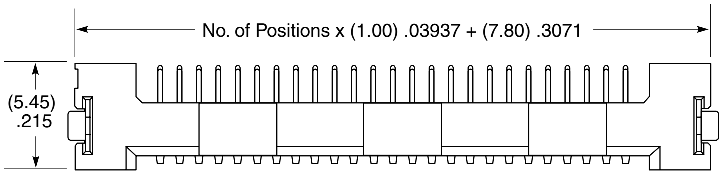
SAL1	-	1	NO. OF POSITIONS	-	01	-	PLATING OPTION	-	S	-	A	-	OPTION
			–20, –27, –30, –40				**–S** = 30 µ" (0.76 µm) Gold on contact, Matte tin on tail						**–TR** = Tape & Reel **–FR** = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks)

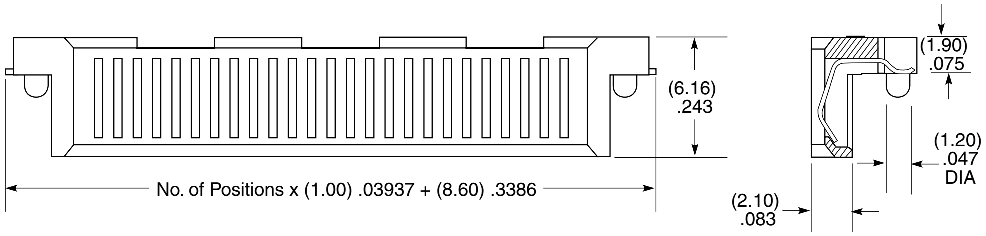
SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
BeCu
Plating:
Au or Sn over 50 µ" (1.27 µm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating:
2.9 A per pin
(2 adjacent pins powered)

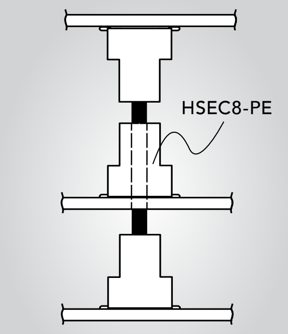
PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max



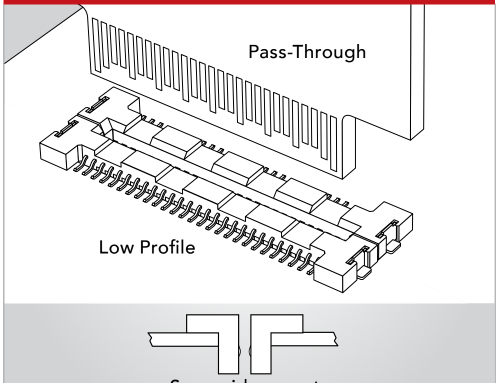


OTHER SOLUTION



Card pass-through option.
See HSEC8-PE Series.

APPLICATIONS



Same side mount

Notes:
While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications..

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?SAL1